

ON Semiconductor				10/16/2019
Base Part		NVB25P06	HF	
Orderable Part		NVB25P06T4G	Total weight (mg)	1420
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	0.19	Silicon (Si)	7440-21-3	100
Die Attach	11.34	Lead (Pb)	7439-92-1	95
		Tin (Sn)	7440-31-5	5
Lead Frame	851.91	Nickel (Ni)	7440-02-0	0.3
		Copper (Cu)	7440-50-8	99.7
Mold Compound-Black	529.31	Epoxy resins	n/a	7
		Phenolic Resin	n/a	7
		Silica Amorphous (SiO2)	7631-86-9	15
		Carbon Black (C)	1333-86-4	0.5
		Fused Silica (SiO2)	60676-86-0	70.5
Plating	27.15	Tin (Sn)	7440-31-5	100
Wire Bond - Al	0.1	Aluminum (Al)	7429-90-5	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels of dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				